



UMC Orders Multiple Applied Materials' Mirra Mesa CMP Systems for New Production Line

March 28, 2000

SANTA CLARA, Calif.--(BUSINESS WIRE)--March 28, 2000--

Mirra Mesa Systems Integrate CMP and Cleaning for
Optimal Technology, Productivity and Space Efficiency

Applied Materials, Inc. today announced that United

Microelectronics Company (UMC), located in Hsinchu, Taiwan, has ordered multiple dry-in/dry-out Mirra Mesa(TM) CMP systems for its newest, most advanced Fab 8D production line. UMC selected the integrated Mirra Mesa CMP system because it offers the advantages of leading-edge polishing and cleaning processes with the industry's highest wafer throughput per square foot. Applied Materials began shipping the Mirra Mesa systems to UMC Fab 8D in December 1999.

"After an extensive evaluation process, we determined that the Mirra Mesa dielectric CMP system offers the most complete and cost-effective solution for our volume manufacturing needs," said Dr. J.J. Lee, deputy director of UMC Fab 8D. "Optimizing manufacturing efficiencies is essential to our operations and by delivering production proven CMP process results in a minimum amount of cleanroom space, the integrated Mirra Mesa system will enable us to improve process precision and overall productivity."

The Mirra Mesa CMP system offers a complete automated dry-in/dry-out post-CMP cleaning process that delivers outstanding particle performance. The Mesa(TM) cleaner can be flexibly configured with up to four separate process modules: a single-wafer immersion megasonic module for maximum cleaning efficiency, two double-sided brush scrubber stations and a spin rinse dryer.

"We are extremely pleased UMC has selected the Mirra Mesa CMP system in their new flagship fab," said Chris Smith, vice president and general manager of Applied Materials' CMP Division. "Since the introduction of the Mirra system almost three years ago, we have continually improved the system to provide more value to our customers. We believe we have achieved a new integrated CMP standard for the industry that addresses our customers' need for advanced dielectric and copper CMP technology in a single compact, cost-effective solution."

Targeted for all CMP applications, the Mirra Mesa systems support the entire range of dielectric and metal materials including copper, oxide, tungsten and polysilicon. Applied Materials is recognized as the world's leading manufacturer of CMP technology with more than 500 Mirra(R) systems currently installed by customers in the U.S., Europe, Japan, Taiwan, and Korea.

According to market research firm Dataquest, the market for CMP systems was estimated to be \$1.04 billion in 1999 and is expected to grow to \$2.5 billion by the year 2004, making it one of the strongest growing segments of the semiconductor equipment market.

Applied Materials, Inc. is a Fortune 500 global growth company and the world's largest supplier of wafer fabrication systems and services to the global semiconductor industry. Applied Materials is traded on the Nasdaq National Market System under the symbol "AMAT." Applied Materials' web site is <http://www.appliedmaterials.com>.

CONTACT: Applied Materials, Inc.
Connie Duncan, 408/563-6209 (editorial/media)
Carolyn Schwartz, 408/748-5227 (financial community)